

# IRLIZ44A-VB Datasheet N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	60	60			
$R_{DS(on)}\left(\Omega\right)$	V <sub>GS</sub> = 10 V	0.027			
Q <sub>g</sub> (Max.) (nC)	95	95			
Q <sub>gs</sub> (nC)	27	27			
Q <sub>gd</sub> (nC)	46	46			
Configuration	Sing	Single			

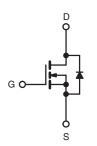
#### **FEATURES**

- Isolated Package
- High Voltage Isolation = 2.5 kV<sub>RMS</sub> (t = 60 s;



- Sink to Lead Creepage Distance = 4.8 mm
- 175 °C Operating Temperature
- · Dynamic dV/dt Rating
- · Low Thermal Resistance
- Lead (Pb)-free Available





N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> T <sub>C</sub> = 25 °C, unless otherwise noted						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			$V_{DS}$	60	V	
Gate-Source Voltage			$V_{GS}$	± 20		
Continuous Drain Current	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C	I <sub>D</sub>	45		
	VGS at 10 V	T <sub>C</sub> = 100 °C		30	Α	
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	220		
Linear Derating Factor				0.32	W/°C	
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	100	mJ	
Maximum Power Dissipation	T <sub>C</sub> =	25 °C	$P_{D}$	52	W	
Peak Diode Recovery dV/dtc			dV/dt	4.5	V/ns	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	- °C	
Soldering Recommendations (Peak Temperature)	for 10 s			300 <sup>d</sup>		
Mounting Torque	6 32 or l	6-32 or M3 screw		10	lbf ⋅ in	
	0-32 of M3 Screw			1.1	N · m	

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b.  $V_{DD}=25$  V, starting  $T_J=25$  °C, L=129  $\mu H,~R_G=25$   $\Omega,~I_{AS}=30$  A (see fig. 12). c.  $I_{SD}\leq 52$  A,  $dI/dt\leq 250$  A/ $\mu s,~V_{DD}\leq V_{DS},~T_J\leq 175$  °C.
- d. 1.6 mm from case.



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	65	°C/W	
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	3.1	C/VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							•
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> :	60	-	-	V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	-	0.060	-	V/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	1.0	-	3.0	V	
Gate-Source Leakage	I <sub>GSS</sub>	,	-	-	± 100	nA	
Zara Cata Valtana Desir O		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V		-	-	25	μΑ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C		-	-	250	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 18 A <sup>b</sup>	-	0.027	-	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 25 V, I <sub>D</sub> = 18 A <sup>b</sup>		15	-	-	S
Dynamic							•
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ $f = 1.0 \text{ MHz}, \text{ see fig. 5}$ $f = 1.0 \text{ MHz}$		-	1500	-	- pF
Output Capacitance	C <sub>oss</sub>			-	720	-	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	100	-	
Drain to Sink Capacitance	С			-	12	-	
Total Gate Charge	Qg		I <sub>D</sub> = 52 A, V <sub>DS</sub> = 48 V, see fig. 6 and 13 <sup>b</sup>	-	-	95	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V		-	-	27	
Gate-Drain Charge	Q <sub>gd</sub>	1		-	-	46	
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{DD}$ = 30 V, $I_{D}$ = 52 A, $R_{G}$ = 9.1 Ω, $R_{D}$ = 0.54 Ω, see fig. 10 <sup>b</sup>		-	19	-	- ns
Rise Time	t <sub>r</sub>			-	120	-	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	55	-	
Fall Time	t <sub>f</sub>			-	86	-	
Internal Drain Inductance	L <sub>D</sub>	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	-11
Internal Source Inductance	L <sub>S</sub>			-	7.5	-	nH
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the		-	-	45	Α
Pulsed Diode Forward Current <sup>a</sup>	I <sub>SM</sub>	integral reverse p - n junction diode		-	-	120	
Body Diode Voltage	$V_{SD}$	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 30 A, V <sub>GS</sub> = 0 V <sup>b</sup>		-	-	2.5	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			-	140	300	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$			-	1.2	2.8	μC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic tu	ırn-on time is negligible (turr	-on is don	ninated by	$L_{\rm S}$ and $L$	_D)

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b. Pulse width  $\leq$  300  $\mu$ s; duty cycle  $\leq$  2 %.



#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

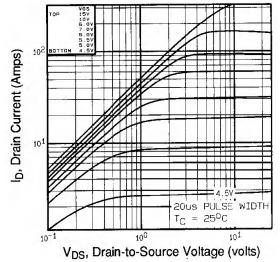


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C

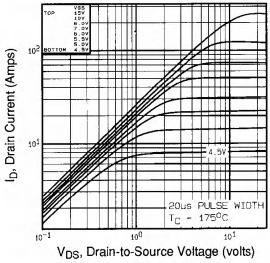


Fig. 2 - Typical Output Characteristics, T<sub>C</sub> = 175 °C

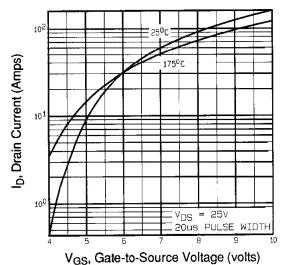


Fig. 3 - Typical Transfer Characteristics

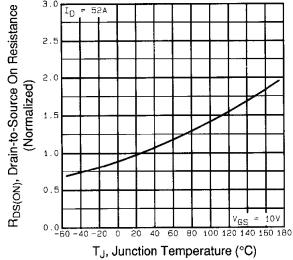


Fig. 4 - Normalized On-Resistance vs. Temperature



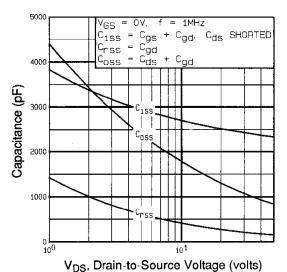


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

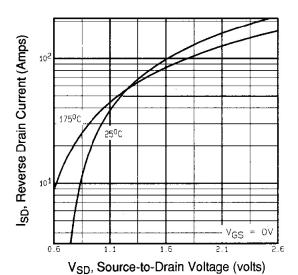


Fig. 7 - Typical Source-Drain Diode Forward Voltage

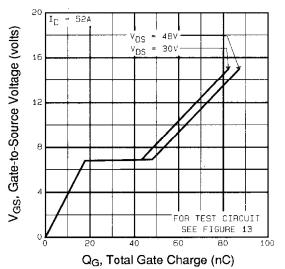
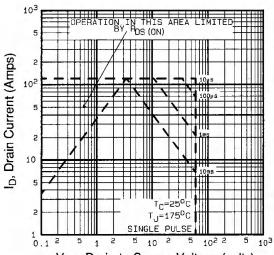


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



 $V_{DS}$ , Drain-to-Source Voltage (volts) Fig. 8 - Maximum Safe Operating Area



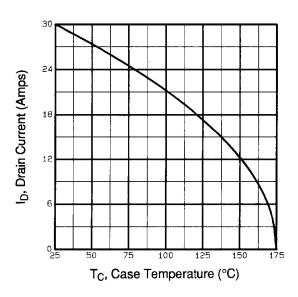


Fig. 9 - Maximum Drain Current vs. Case Temperature

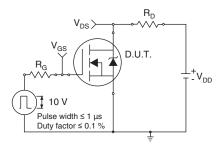


Fig. 10a - Switching Time Test Circuit

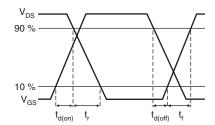


Fig. 10b - Switching Time Waveforms

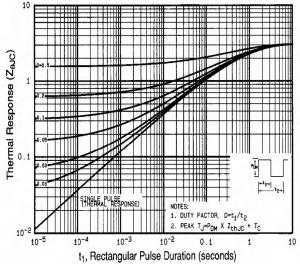


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

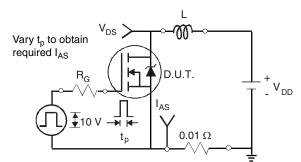


Fig. 12a - Unclamped Inductive Test Circuit

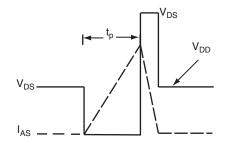
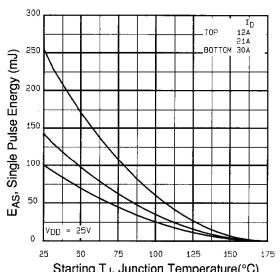


Fig. 12b - Unclamped Inductive Waveforms





 $Starting \ T_J, \ Junction \ Temperature (^{\circ}C)$  Fig. 12c - Maximum Avalanche Energy vs. Drain Current

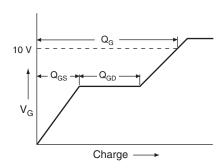


Fig. 13a - Basic Gate Charge Waveform

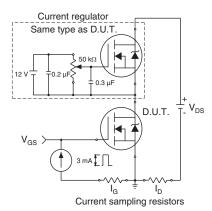
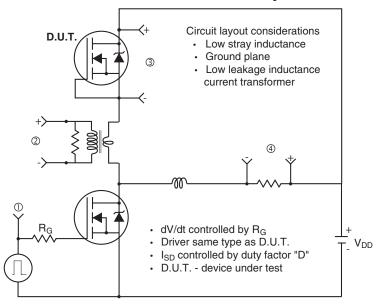
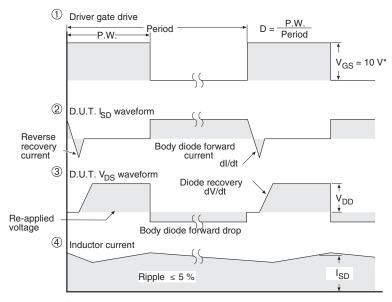


Fig. 13b - Gate Charge Test Circuit



### Peak Diode Recovery dV/dt Test Circuit





\*  $V_{GS} = 5 V$  for logic level devices

Fig. 14 - For N-Channel



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